ABSTRACT

SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME, APPARATUS FOR MANUFACTURING SEMICONDUCTOR DEVICE, CIRCUIT BOARD, AND ELECTRONIC INSTRUMENT

A method of manufacturing a semiconductor device comprising the steps of: preparing a flexible substrate which includes a base substrate having a light transmission property and an interconnecting pattern formed on one surface of the base substrate, the flexible substrate allowing a light to pass through a region other than the interconnecting pattern; recognizing a position of the interconnecting pattern by viewing the flexible substrate from a surface opposite to the surface on which the interconnecting pattern is formed through the base substrate; recognizing positions of electrodes formed on a semiconductor chip from a direction identical to that in recognizing the interconnecting pattern; and aligning the interconnecting pattern with the electrodes to connect the flexible substrate to the semiconductor chip by the face down bonding.

FIG. 1A